

Product / Package Information

Package	SC70- COL
Body Size	
Lead Count	6
Terminal Finish	NiPdAu
MS Number	MS011457A

Environmental Compliance Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	3.07 E-03	88.00	880000	45.02	450176
Thermosets	Epoxy & Phenol resin	Proprietary	4.02 E-04	11.50	115000	5.88	58830
Other inorganic materials	Carbon black	1333-86-4	1.75 E-05	0.50	5000	0.26	2558
Subtotal			3.49 E-03	100.0	1000000	51.16	511564

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	2.95 E-03	97.5	975000	43.16	431635
Copper & its alloys	Iron	7439-89-6	7.10 E-05	2.35	23500	1.04	10403
Copper & its alloys	Zinc	7440-66-6	3.63 E-06	0.12	1200	0.05	531
Copper & its alloys	Phosphorus	7723-14-0	9.07 E-07	0.03	300	0.01	133
Subtotal			3.02 E-03	100	1000000	44.27	442702

Internal/External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Nickel & its alloys	Nickel	7440-02-0	3.52 E-05	90.91	909091	0.52	5156
Precious metals	Palladium	7440-05-3	3.06 E-06	7.91	79051	0.04	448
Precious metals	Gold	7440-57-5	4.59 E-07	1.19	11858	0.01	67
Subtotal			3.87 E-05	100.00	1000000	0.57	5672

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	2.08 E-05	99	990000	0.31	3051
Precious metals	Palladium	7440-05-3	2.10 E-07	1	10000	0.003	31
Subtotal			2.10 E-05	100	1000000	0.31	3082

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.21 E-04	100	1000000	3.24	32358

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Aluminum oxide	1344-28-1	1.10 E-05	35	350000	0.16	1618
Other organic materials	Diethylene glycol monoethyl ether acetate	112-15-2	1.10 E-05	35	350000	0.16	1618
Thermoset	Epoxy Resin	TS ref# 10114 /	7.89 E-06	25	250000	0.12	1156
Others	Amine	TS ref# 10105 / TS ref# 10039	1.58 E-06	5	50000	0.02	231
Subtotal			3.16 E-05	100	1000000	0.46	4623

Package Totals	Weight (g)	Percentage (%)	PPM
	6.83 E-03	100	1000000

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ADI Proprietary

Product / Package Information

Package	SC70 - Isolated Backside
Body Size	
Lead Count	3
Terminal Finish	100 Sn
MS Number	MS011467A

Environmental Compliance Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	2.47 E-03	87.30	873000	45.12	451231
Thermosets	Phenol Resin	Proprietary	1.27 E-04	4.50	45000	2.33	23259
Thermosets	Epoxy Resin 1	Proprietary	8.49 E-05	3.00	30000	1.55	15506
Thermosets	Epoxy Resin 2	Proprietary	8.49 E-05	3.00	30000	1.55	15506
Others	Others	Proprietary	5.66 E-05	2.00	20000	1.03	10337
Other inorganic materials	Carbon Black	1333-86-4	5.66 E-06	0.20	2000	0.10	1034
Subtotal			2.83 E-03	100.0	1000000	51.69	516874

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	2.12 E-03	97.5	975000	38.78	387847
Copper & its alloys	Iron	7439-89-6	5.12 E-05	2.35	23500	0.93	9348
Copper & its alloys	Zinc	7440-66-6	2.61 E-06	0.12	1200	0.05	477
Copper & its alloys	Phosphorus	7723-14-0	6.53 E-07	0.03	300	0.01	119
Subtotal			2.18 E-03	100	1000000	39.78	397792

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.20 E-05	100	1000000	0.40	4018

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	1.75 E-04	100	1000000	3.20	32002

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	3.00 E-05	99.99	1000000	0.55	5479

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.10 E-04	100	1000000	3.84	38355

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silicon Dioxide	14808-60-7	1.50 E-05	49.90	499000	0.27	2734
Organic materials	Reaction product: bisphenol-F-(epichlorohydrin); epoxy resin (number average molecular weight <= 700)	9003-36-5	6.00 E-06	20.00	200000	0.11	1096
Organic materials	1,4-bis(2,3-epoxypropoxy)butane	2425-79-8	6.00 E-06	20.00	200000	0.11	1096
Others	Aromatic Amine	Proprietary	1.50 E-06	5.00	50000	0.03	274
Glass	Glass	65997-17-3	1.50 E-06	5.00	50000	0.03	274
Organic materials	Reaction product: bisphenol-A-(epichlorohydrin); epoxy resin (number average molecular weight <= 700)	25068-38-6	3.00 E-08	0.10	1000	0.0005	5
Subtotal			3.00 E-05	100.00	1000000	0.55	5479

Package Totals	Weight (g)	Percentage (%)	PPM
	5.48 E-03	100	1000000

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ADI Proprietary

Product / Package Information

Package	SC70 - Isolated Backside
Body Size	
Lead Count	3
Terminal Finish	SnPb
MS Number	MS011469A

Environmental Compliance Information

RoHS Compliant	No
High Temperature Compliant	No
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	2.47 E-03	87.30	873000	45.12	451231
Thermosets	Phenol Resin	Proprietary	1.27 E-04	4.50	45000	2.33	23259
Thermosets	Epoxy Resin 1	Proprietary	8.49 E-05	3.00	30000	1.55	15506
Thermosets	Epoxy Resin 2	Proprietary	8.49 E-05	3.00	30000	1.55	15506
Others	Others	Proprietary	5.66 E-05	2.00	20000	1.03	10337
Other inorganic materials	Carbon Black	1333-86-4	5.66 E-06	0.20	2000	0.10	1034
Subtotal			2.83 E-03	100.0	1000000	51.69	516874

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Subtotal			2.18 E-03	100	1000000	39.78	397792

Internal Leadframe Plating

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				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.20 E-05	100	1000000	0.40	4018

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	1.49 E-04	85.00	850000	2.72	27202
Tin & its alloys	Lead	7439-92-1	2.63 E-05	15.00	150000	0.48	4800
Subtotal			1.75 E-04	100	1000000	3.20	32002

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	3.00 E-05	99.99	1000000	0.55	5479

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
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Organic materials	1,4-bis(2,3-epoxypropoxy)butane	2425-79-8	6.00 E-06	20.00	200000	0.11	1096
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Glass	Glass	65997-17-3	1.50 E-06	5.00	50000	0.03	274
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